



**Materials Declaration**

<b>Package</b>	Sidebrazed
<b>Body Size</b>	300 mils
<b>Lead Count</b>	14
<b>Option</b>	SnPb

<b>Combolid</b>			
Item	% of Combolid	Weight (g)	PPM
Kovar	92	1.63E-01	125791
Nickel	4	7.08E-03	5469
Gold	4	7.08E-03	5469
Subtotal		1.77E-01	136730

<b>Lid Frame</b>			
Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.19 E-02	9221
Sn	20.42	3.06 E-03	2366
Subtotal		1.50 E-02	11587

<b>Ceramic Package</b>			
Item	% of Ceramic	Weight (g)	PPM
Al2O3	77.0	8.19 E-01	632880
Iron	6.3	6.71 E-02	51863
Nickel	4.9	5.17 E-02	39945
Chromium	3.3	3.52 E-02	27206
SiO2	3.0	3.21 E-02	24822
Co,Ag,Cu,MgO, CaO	2.9	3.06 E-02	23671
Tungsten	2.5	2.66 E-02	20548
Gold	0.2	1.70 E-03	1315
Subtotal		1.06 E+00	822251

<b>Bond Wires</b>			
Item	% of Wire	Weight (g)	PPM
Aluminum	100	1.20 E-03	927

<b>Chip 1</b>			
Item	% of Chip	Weight (g)	PPM
Si	100	6.70 E-03	5176

<b>Solder</b>			
Item	% of Solder	Weight (g)	PPM
Tin	63	1.83 E-02	14113
Lead	37	1.07 E-02	8289
Subtotal		2.90 E-02	22402

<b>Die Attach Paste</b>			
Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80	9.60 E-04	742
Cyanate ester resin	20	2.40 E-04	185
Subtotal		1.20 E-03	927

<b>Package Totals</b>	
Weight (g)	PPM
<b>1.29E+00</b>	<b>1000000</b>

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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